

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2903	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 17:36
L2	4150	257/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L3	1908	257/690.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L4	1954	257/692.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L5	375	257/672.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L6	380	257/674.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L7	501	257/673.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L8	528	257/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05

EAST Search History

L9	2432	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L10	12200	1 2 3 4 5 6 7 8 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:05
L11	6113	10 and (recession or recess or trench or groove or via or slit or slot)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 16:06
L12	1162	11 and (passive or capacitor or resistor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:06
L13	1381	11 and (passive or capacitor or resistor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 16:06
L14	2619	(lead adj frame) and (passive or capacitor or resistor or inductor) and (semiconductor or ic or die or chip) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 16:55
L15	2619	14 not "13."	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 16:55
L16	2332	14 not 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 17:14

EAST Search History

L17	1423	14 not 13	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/23 16:55
L18	909	14 not 13	US-PGPUB	OR	ON	2006/07/23 17:14
L19	853	257/782.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:27
L20	828	19 not 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 17:36
L21	795	20 not 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 17:37
L22	161	257/e23.031.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:27
L23	717	257/e23.037.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:27
L24	1384	257/e23.039.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:27
L25	2224	22 23 24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:27

EAST Search History

L26	1167	25 not 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:28
L27	1152	26 not 19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:28
L28	1100	27 not 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 18:28
S1	2371	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:04
S2	1467	S1 and (recession or recess or trench or groove or via or slit or slot)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:06
S5	4986	"257"/\$6.ccls. and (((die adj pad) or (lead adj frame)) and (recession or recess or trench or groove or via or slit or slot) and (ic or chip or die or semiconductor or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 13:59
S6	2765	S5 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 14:04
S7	1803	S5 and solder	USPAT	OR	OFF	2005/03/19 15:15
S8	3785	257/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/11 14:19

EAST Search History

S9	448	257/673.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:54
S10	1	"6521982".PN.	USPAT; USOCR	OR	OFF	2005/03/19 16:29
S11	1	"6459147".PN.	USPAT; USOCR	OR	OFF	2005/03/19 16:29
S12	1	"6256200".PN.	USPAT; USOCR	OR	OFF	2005/03/19 17:02
S13	1	"6255672".PN.	USPAT; USOCR	OR	OFF	2005/03/19 17:02
S14	1	"6252300".PN.	USPAT; USOCR	OR	OFF	2005/03/19 17:05
S15	4986	"257"/\$6.ccls. and (((die adj pad) or (lead adj frame)) and (recession or recess or trench or groove or via or slit or slot) and (ic or chip or die or semiconductor or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 17:55
S16	1803	S15 and solder	USPAT	OR	OFF	2005/03/19 17:55
S17	3785	257/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 17:55
S18	3455	S17 not S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 17:56
S19	3355	S18 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 17:57
S20	789	S19 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 17:57

EAST Search History

S21	66	(die adj pad) and (recess near3 lead)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:45
S22	1740	257/692.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:54
S23	1654	257/690.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:55
S24	343	257/672.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:12
S25	346	257/674.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:55
S26	657	S24 or S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:55
S27	606	S26 not S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:55
S28	536	S27 not S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:55

EAST Search History

S29	487	S28 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 18:56
S30	3150	S22 or S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:12
S31	1394	S30 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:12
S32	175	S31 and recess	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:14
S33	3713	S30 or S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:14
S34	65	S33 and (solder near5 (wire near2 bonding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:18
S35	26	S34 and (solder WITH (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:27
S36	101	(lead adj frame) and (solder near5 (wire near2 bonding)) and (solder same (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:02

EAST Search History

S37	91	S36 not S35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:18
S38	264	(lead adj frame) and (solder near5 wire) and (solder same (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:52
S39	2371	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:38
S40	556	S39 and (solder WITH (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:29
S41	26	257/672.ccls. and (solder WITH (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:29
S42	1000	((solder near5 wire) same lead) and (solder same (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:52
S43	522	((solder near5 wire) with lead) and (solder near5 (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/19 21:53
S44	3947	257/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:38

EAST Search History

S45	500	257/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:38
S46	360	257/672.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:38
S47	475	257/673.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:38
S48	2272	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 12:56
S49	6218	S44 S45 S46 S47 S48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:39
S50	580	S49 and (recess or recesses)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 13:06
S51	465	(lead adj frame) and (passive or capacitor or resistor or inductor) and (semiconductor or ic or die or chip) and (solder same (sn or tin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:57
S52	457	S51 not S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:04

EAST Search History

S53	1797	(lead adj frame) and (passive or capacitor or resistor or inductor) and (semiconductor or ic or die or chip) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:55
S54	1340	S53 not S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:57
S55	1332	S54 not S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:58
S56	1319	S55 not S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 11:58
S57	2356	S50 S51 S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 12:57
S58	1962	S48 not S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 12:57
S59	552	S49 and (passive or capacitor or resistor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/23 16:06
S60	375	S59 not S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 13:06

EAST Search History

S61	4011	257/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/11 14:19
S62	1311	S61 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/11 14:19
S63	2707	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/11 14:22
S64	2215	S63 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/11 14:23
S65	316	S63 and passive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/11 14:23
S66	799	257/782.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/12 17:18
S67	144	S66 and (passive or resistor or capacitor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:18
S68	454	(die adj pad) and (solder) and (lead) and (semiconductor or die or ic or chip or (integrated adj die)) and (passive or resistor or capacitor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:20

EAST Search History

S69	444	S68 not S67	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 15:50
S70	208	(die adj (pad or paddle)) and (solder) and (lead) and ((flip adj chip) or flipchip) and (passive or resistor or capacitor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:09
S71	588	S67 S68	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:09
S72	45	S70 not S71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:09
S73	2733	257/678.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/12 17:18
S74	633	S71 S72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/12 17:18
S75	2695	S73 not S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/12 17:18
S76	559	S75 and (passive or resistor or capacitor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:21

EAST Search History

S77	1589	S75 and (lead)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:21
S78	349	S77 and (passive or resistor or capacitor or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:47
S79	1240	S77 not S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 17:47
S80	1	("6507120").PN.	USPAT	OR	OFF	2006/01/13 09:40
S82	336	(die adj pad) with (ground or gnd)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/13 10:49
S83	20	(lead adj frame) near5 (conductive adj pattern)	USPAT	OR	OFF	2006/06/06 12:21